

■ Thin-film Laser Marking System (Removal Method Type)



Rectangular-shaped laser beam realizes a beautiful scribing line.

Features

This system removes thin films covered on a surface of transparent glass at first and marks letters and 2D codes on it.

- Multiple laser heads ensures a high throughput.
- Employ a software with Image alignment system.
- Inner marking on a layered substrate is possible.

Specifications

Substrate size	Up to the eighth generation (Thickness: 0.4 x 1 to 1.1 x 2mm)
Takt time	200sec. (G8, 30 surfaces, 2 heads)
Marking positioning accuracy	80 μ m
Workpiece conveying method	Belt conveyor and robot
Dimensions	3000W x 6500D x 3000H mm (In case of the eighth generation)